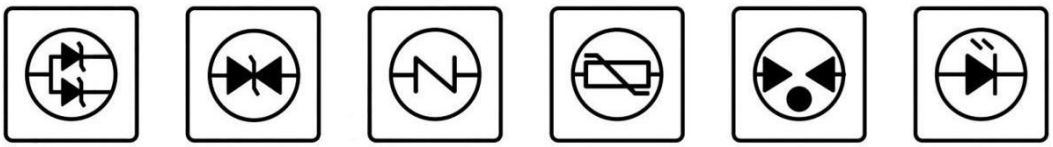
MSKSEMI 美森科
SEMICONDUCTOR

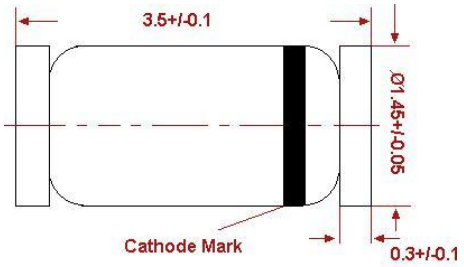


LL4148-MS

Product specification

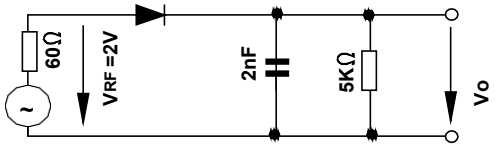
Features

- power dissipation
- IF:200mA
- VR:75V
- PKG:LL34 glass case



Glass case MiniMELF
Dimensions in mm

LL-34



Rectification Efficiency Measurement Circuit

REEL SPECIFICATION

P/N	PKG	QTY
LL4148-MS	LL-34	2500

Absolute Maximum Ratings (Ta = 25℃)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	75	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non-repetitive Peak Forward Surge Current at t = 1 s at t = 1 ms at t = 1 µs	I_{FSM}	0.5 1 4	A
Power Dissipation	P_{tot}	500 [1]	mW
Junction Temperature	T_j	175	°C
Storage Temperature Range	T_{stg}	- 65 to + 175	°C

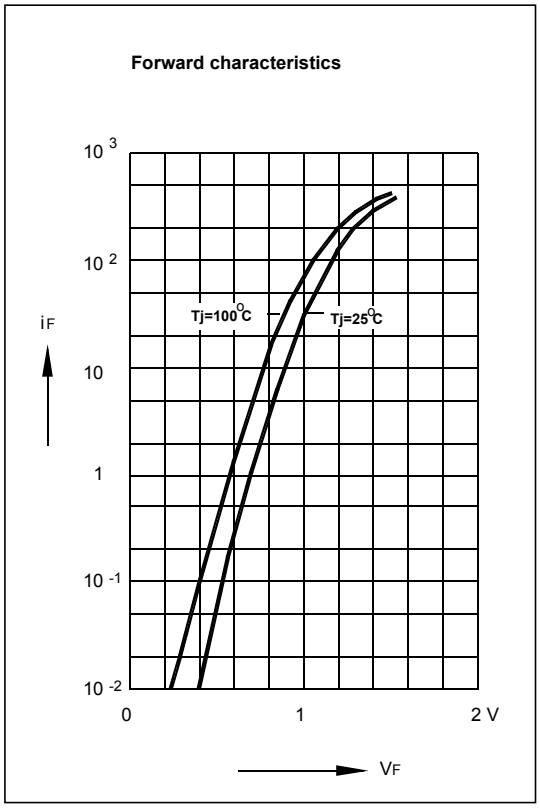
[1] Valid provided that electrodes are kept at ambient temperature.

Characteristics at Ta = 25℃

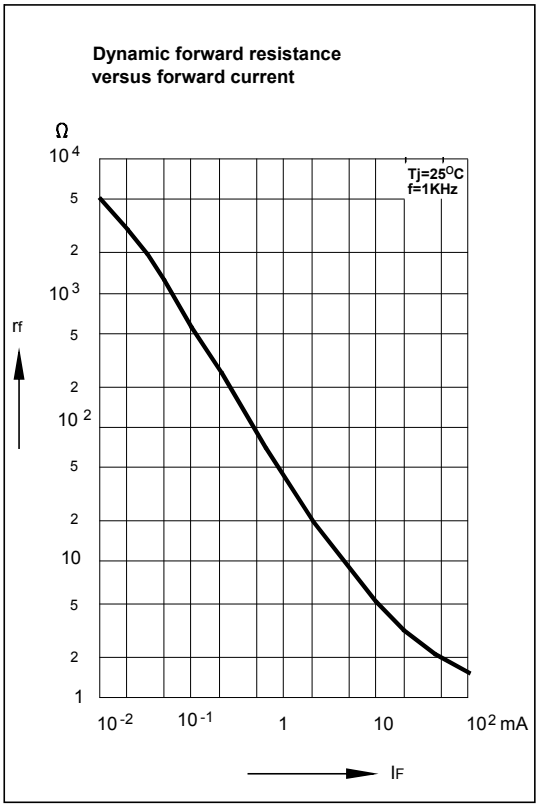
Parameter	Symbol	Min.	Max.	Unit
Forward Voltage at I_F = 10 mA	V_F	-	1	V
Leakage Current at V_R = 20 V at V_R = 75 V at V_R = 20 V, T_j = 150 °C	 I_R I_R I_R	 - - -	 25 5 50	 nA µA µA
Reverse Breakdown Voltage tested with 100 µA Pulses	$V_{(BR)R}$	100	-	V
Capacitance at V_R = 0, f = 1 MHz	C_{tot}	-	4	pF
Voltage Rise when Switching ON tested with 50 mA Forward Pulses tp = 0.1 s, Rise Time < 30 ns, fp = 5 to 100 KHz	V_{fr}	-	2.5	V
Reverse Recovery Time at I_F = 10 mA to I_R = 1 mA, V_R = 6 V, R_L = 100 Ω	t_{rr}	-	4	ns
Thermal Resistance Junction to Ambient Air	R_{thA}	-	0.35 [1]	K/mW
Rectification Efficiency at f = 100 MHz, V_{RF} = 2 V	η_V	0.45	-	-

[1] Valid provided that electrodes are kept at ambient temperature.

Forward characteristics

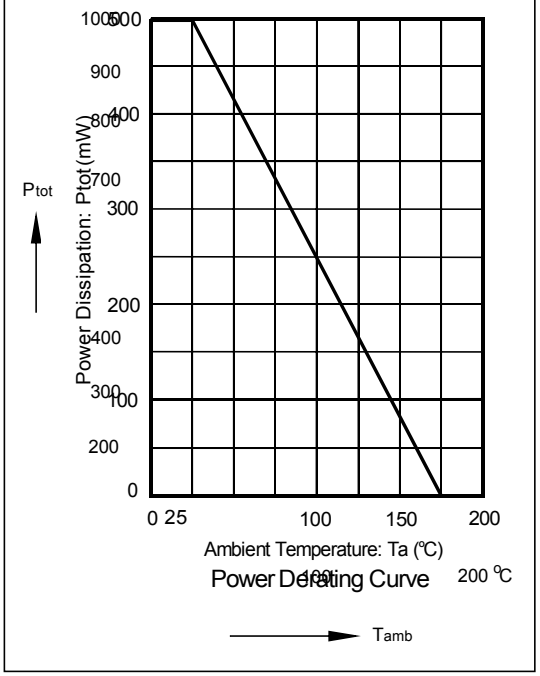


Dynamic forward resistance versus forward current

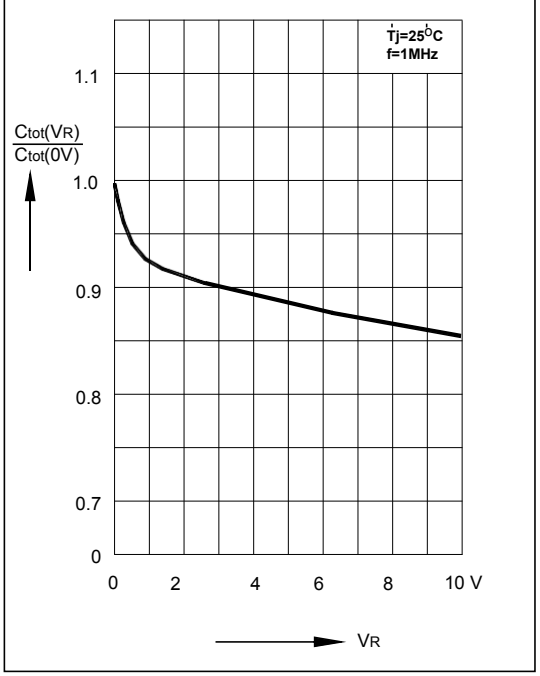


Admissible power dissipation versus ambient temperature

Valid provided that electrodes are kept at ambient temperature



Relative capacitance versus reverse voltage



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